

Features :

- Isolated mounting base 3000V~
- Solder joint technology with increased power cycling capability
- Space and weight saving

Typical Applications :

- Various rectifiers
- DC supply for PWM inverter

V _{RSM}	V _{R_{RRM}}	品名
700V	600V	MD200D60S
900V	800V	MD200D80S
1100V	1000V	MD200D100S
1300V	1200V	MD200D120S
1500V	1400V	MD200D140S
1700V	1600V	MD200D160S
1900V	1800V	MD200D180S

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _j (°C)	VALUE			UNIT
				Min	Type	Max	
I _{F(AV)}	Mean forward current	180° half sine wave 50Hz Single side cooled, T _C =100°C	150			200	A
I _{F(RMS)}	RMS forward current					314	A
I _{R_{RRM}}	Repetitive peak current	at V _{R_{RRM}}	150			12	mA
I _{F_{SM}}	Surge forward current	10ms half sine wave V _R =0.6V _{R_{RRM}}	150			4	kA
I ² t	I ² t for fusing coordination					80	10 ³ A ² s
V _{FO}	Threshold voltage		150			0.78	V
r _F	Forward slope resistance					1.10	mΩ
V _{FM}	Peak forward voltage	I _{FM} =600A	25			1.60	V
R _{th(j-c)}	Thermal resistance Junction to case	D.C. Single side cooled per chip				0.18	°C/W
R _{th(c-h)}	Thermal resistance case to heatsink	D.C. Single side cooled per chip				0.08	°C/W
V _{iso}	Isolation voltage	50Hz,R.M.S,t=1min, I _{iso} :1mA(max)		3000			V
F _m	Terminal connection torque(M6)			3.5		5.0	N·m
	Mounting torque(M6)			3.5		5.0	N·m
T _{vj}	Junction temperature			-40		150	°C
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight				165		g
Outline	M17						

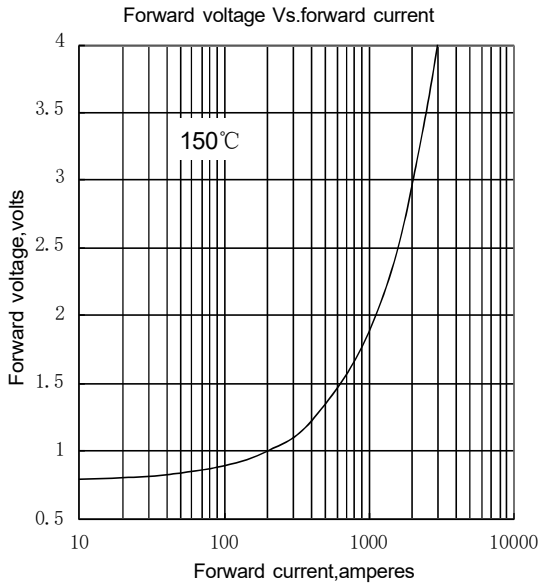


Fig1

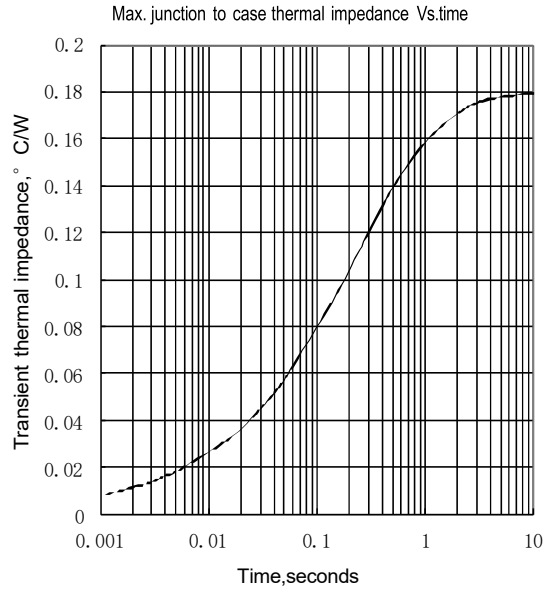


Fig2

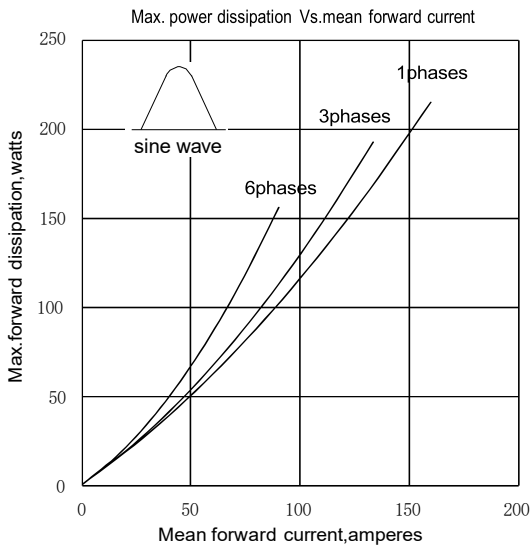


Fig3

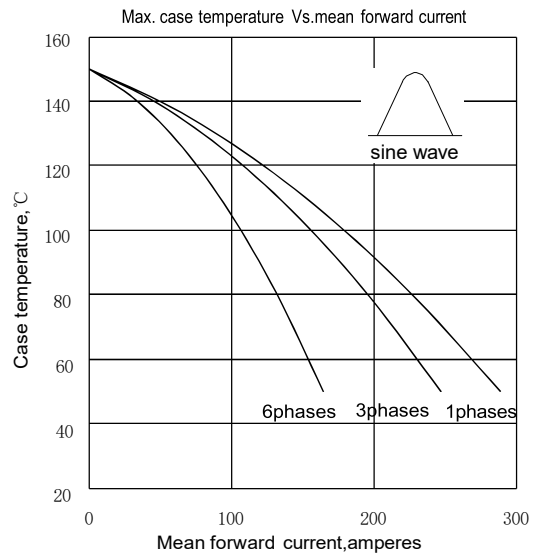


Fig4

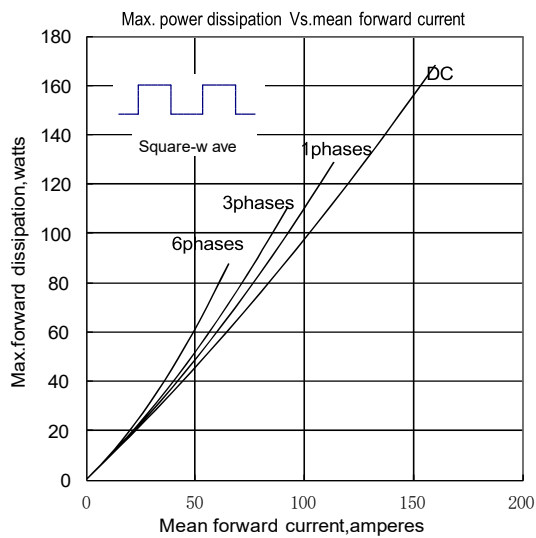


Fig5

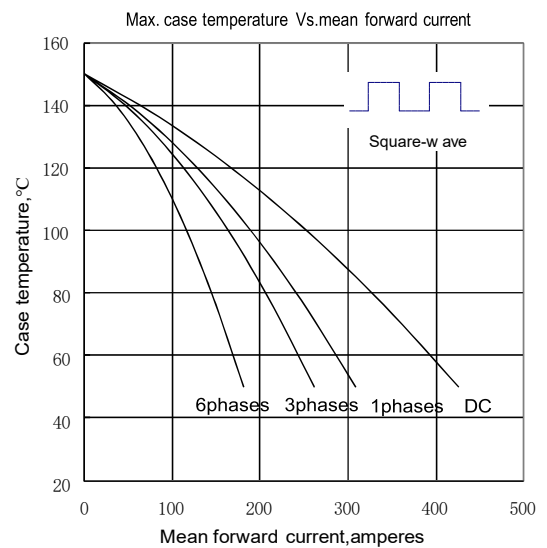


Fig6

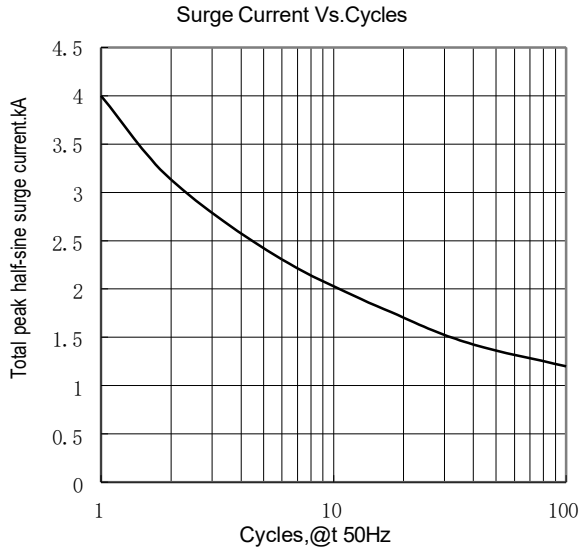
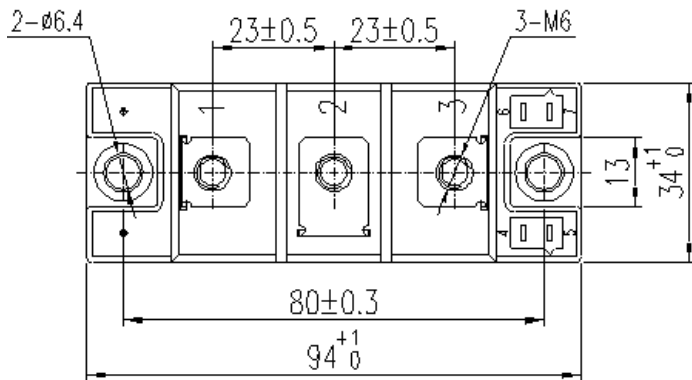
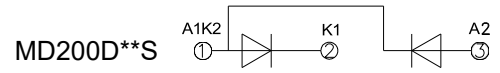
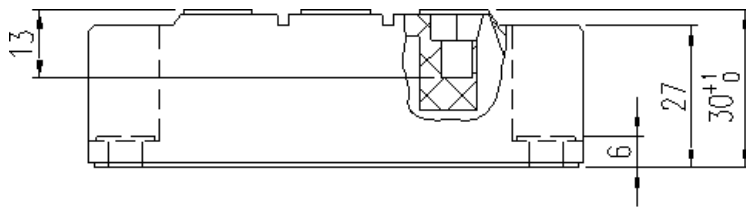


Fig7

Outline:



Unmarked dimensional tolerance: ±0.5mm